

DATA SHEET

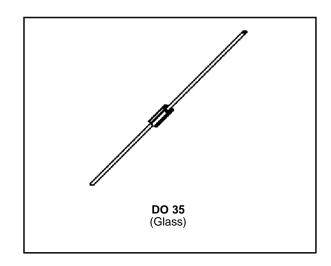
Signal Diodes

Order code	Manufacturer code	Description
47-3104	BAT46	BAT46 100V SILICON SCHOTTKY DIODE

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The enclosed information is believed to be correct, Information may change 'without notice' due to	Revision A
product improvement. Users should ensure that the product is suitable for their use. E. & O. E.	04/07/2003

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SMALL SIGNAL SCHOTTKY DIODE



DESCRIPTION

General purpose, metal to silicon diode featuring high breakdown voltage low turn-on voltage.

ABSOLUTE RATINGS (limiting values)

Symbol	Parameter	Value	Unit	
V_{RRM}	Repetitive Peak Reverse Voltage		100	V
l _F	Forward Continuous Current*	150	mA	
I _{FRM}	Repetitive Peak Forward Current*	350	mA	
I _{FSM}	Surge non Repetitive Forward Current* t _p	750	mA	
P _{tot}	Power Dissipation*	i= 80 °C	150	mW
$T_{stg} \ T_{j}$	Storage and Junction Temperature Range		- 65 to + 150 - 65 to + 125	°C °C
TL	Maximum Temperature for Soldering during 10s at	4mm from Case	230	°C

THERMAL RESISTANCE

Symbol	Test Conditions	Value	Unit
R _{th (j-a)}	Junction-ambient*	300	°C/W

^{*} On infinite heatsink with 4mm lead length

ELECTRICAL CHARACTERISTICS

STATIC CHARACTERISTICS

Symbol	Test Conditions		Min.	Тур.	Max.	Unit
V_{BR}	$T_i = 25^{\circ}C$	$I_R = 10\mu A$	100			V
V _F *	T _i = 25°C	$I_F = 0.1 \text{mA}$			0.25	٧
	T _i = 25°C	$I_F = 10mA$			0.45	
	T _i = 25°C	$I_F = 250 \text{mA}$			1	
I _R *	T _i = 25°C	V _R = 1.5V			0.5	μΑ
	$T_i = 60^{\circ}C$				5	
	T _i = 25°C	V _R = 10V			0.8	
	$T_j = 60^{\circ}C$				7.5	
	$T_i = 25^{\circ}C$	$V_R = 50V$			2	
	$T_{i} = 60^{\circ}C$				15	
	T _j = 25°C	$V_R = 75V$			5	
	$T_j = 60^{\circ}C$				20	

DYNAMIC CHARACTERISTICS

Symbol		Min.	Тур.	Max.	Unit		
С	T _j = 25°C	$V_R = 0V$	f = 1MHz		10		pF
	T _j = 25°C	$V_R = 1V$			6		

^{*} Pulse test: $t_p \le 300 \mu s \ \delta < 2\%$.

Figure 1. Forward current versus forward voltage at different temperatures (typical values).

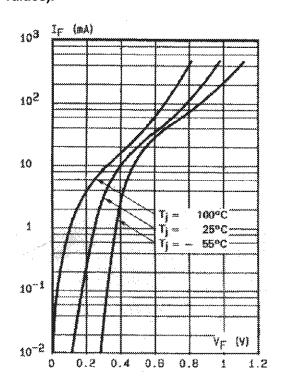


Figure 2. Forward current versus forward voltage (typical values).

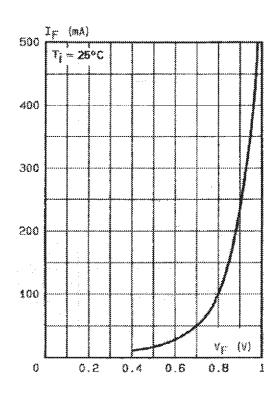
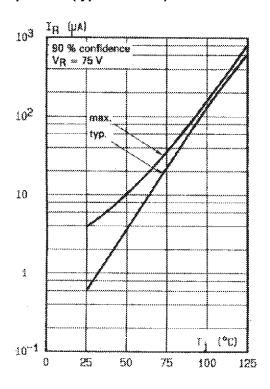


Figure 3. Reverse current versus junction temperature (typical values).

Figure 4. Reverse current versus continuous reverse voltage.



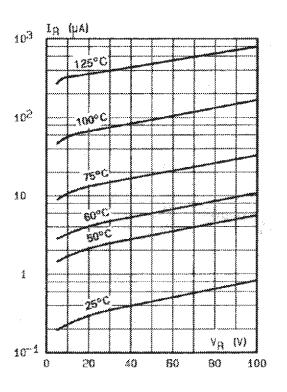
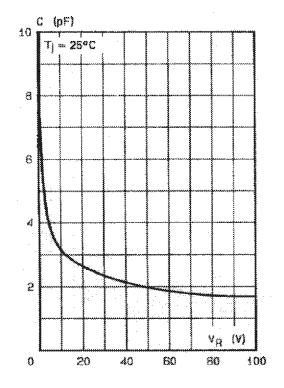
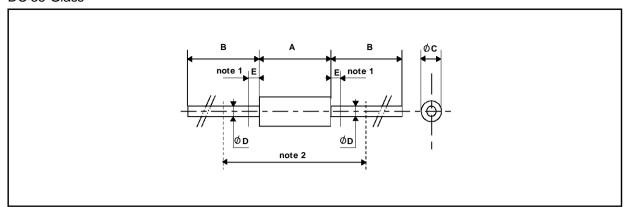


Figure 5. Capacitance C versus reverse applied voltage $V_{\rm R}$ (typical values).



PACKAGE MECHANICAL DATA

DO 35 Glass



	DIMENSIONS					
REF.	EF. Millimeters		s Inches		NOTES	
	Min.	Max.	Min.	Max.		
Α	3.050	4.500	0.120	0.117	1 - The lead diameter Ø D is not controlled over zone E	
В	12.7		0.500			
ØC	1.530	2.000	0.060	0.079	2 - The minimum axial lengh within which the device may be placed with its leads bent at right angles is 0.59"(15 mm)	
ØD	0.458	0.558	0.018	0.022	phaced with its leads bent at right angles is 0.55 (15 min)	
Е		1.27		0.050		

Cooling method: by convection and conduction Marking: ring at cathode end. Weight: 0.05g